

Description

The TP86R203NL uses advanced trench technology

to provide excellent RDS(ON), low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.



SOP-8

PIN2 D

General Features

 $V_{DS} = 30V I_{D} = 15 A$

 $R_{DS(ON)} < 9m\Omega$ @ $V_{GS}=10V$

 $R_{DS(ON)}$ < 14m Ω @ V_{GS} =4.5V



Battery protection

Load switch

Uninterruptible power supply

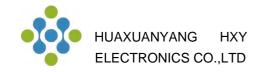
N-Channel MOSFET

Package Marking and Ordering Information

| <u> </u> | | | |
|------------|-------|------------|----------|
| Product ID | Pack | Brand | Qty(PCS) |
| TP86R203NL | SOP-8 | HXY MOSFET | 3000 |

Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

| Symbol | Parameter | Limit | Unit |
|------------------------|---|------------|--|
| Vps | Drain-Source Voltage | 30 | V |
| Vgs | Gate-Source Voltage | ±20 | V |
| I _D | Drain Current-Continuous | 15.0 | Α |
| I _D (70 °C) | Drain Current-Continuous(Tc=70°C) | 8.2 | Α |
| Ірм | Pulsed Drain Current | 42 | Α |
| P _D | Maximum Power Dissipation | 1.5 | W |
| Eas | Single pulse avalanche energy (Note 5) | 62 | mJ |
| TJ,Tstg | Operating Junction and Storage Temperature Range | -55 To 150 | $^{\circ}\!$ |
| Rejc | Thermal Resistance,Junction-to-Case ^(Note 2) | 36 | °C/W |



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit | |
|---|---|--|------|-------|-------|---------------|--|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =250uA | 30 | | | V | |
| $\triangle BV_{DSS}/\triangle T_{J}$ | SS/△T」 BVDSS Temperature Coefficient Reference to 25°C , I _D =1mA | | | 0.027 | | V/°C | |
| В | Static Drain-Source On-Resistance ² | V _{GS} =10V , I _D =10A | | 7.5 | 9 | $$ m Ω | |
| $R_{DS(ON)}$ | | V _{GS} =4.5V , I _D =8A | | 11 | 14 | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | V -V 1 -250··A | 1.2 | 1.5 | 2.5 | V | |
| $\triangle V_{GS(th)}$ | V _{GS(th)} V _{GS(th)} Temperature Coefficient | | | -5.8 | | mV/°C | |
| l | Drain-Source Leakage Current | V _{DS} =24V , V _{GS} =0V , T _J =25°C | | | 1 | uA | |
| I _{DSS} | | V _{DS} =24V , V _{GS} =0V , T _J =55°C | | | 5 | | |
| Igss | Gate-Source Leakage Current | V _{GS} =±20V , V _{DS} =0V | | | ±100 | nA | |
| gfs | Forward Transconductance | V _{DS} =5V , I _D =10A | | 5.8 | | S | |
| Rg | Gate Resistance | V _{DS} =0V , V _{GS} =0V , f=1MHz | | 2.2 | 3.8 | Ω | |
| Qg | Total Gate Charge (4.5V) | | | 12.6 | 17.6 | | |
| Q _{gs} | Gate-Source Charge | V _{DS} =15V , V _{GS} =4.5V , I _D =10A | | 4.2 | 5.9 | nC | |
| Qgd | Gate-Drain Charge | | | 5.1 | 7.1 | | |
| T _{d(on)} | Turn-On Delay Time | | | 6.2 | 12.4 | | |
| Tr | Rise Time | V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω | | 59 | 106 | ns | |
| $T_{d(off)}$ | Turn-Off Delay Time | I _D =10A | | 27.6 | 55 | | |
| Tf | Fall Time | | | 8.4 | 16.8 | | |
| Ciss | Input Capacitance | | | 1317 | 1845 | | |
| Coss | Output Capacitance | V _{DS} =15V , V _{GS} =0V , f=1MHz | | 163 | 228.2 | pF | |
| C _{rss} Reverse Transfer Capacitance | | | | 131 | 183.4 | 1 | |
| Is | Continuous Source Current ^{1,5} |)/ | | | 10.3 | А | |
| I _{SM} | Pulsed Source Current ^{2,5} V _G =V _D =0V , Force Current | | | | 42 | Α | |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V , I _S =1A , T _J =25°C | | | 1.2 | V | |
| t _{rr} | Reverse Recovery Time | | | 12.5 | | nS | |
| Qrr | Reverse Recovery Charge IF=10A , dI/dt=100A/μs , T _J =25°C | | | 5 | | nC | |

Note:

^{1.}The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

^{3.} The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =35A

^{4.} The power dissipation is limited by 150°C junction temperature

^{5.} The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

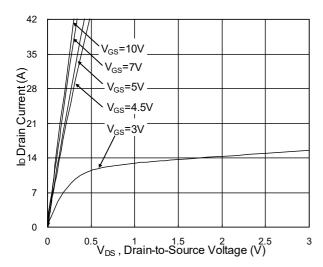


Fig.1 Typical Output Characteristics

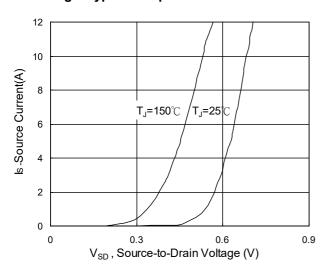


Fig.3 Forward Characteristics of reverse

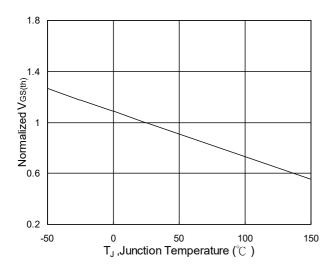


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

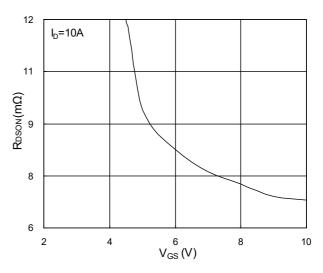


Fig.2 On-Resistance vs. Gate-Source

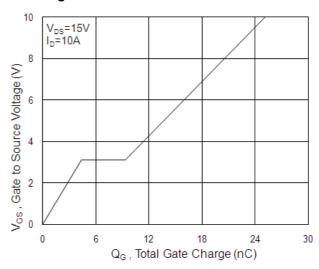


Fig.4 Gate-Charge Characteristics

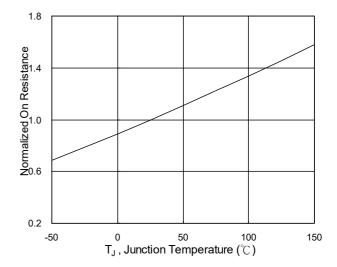
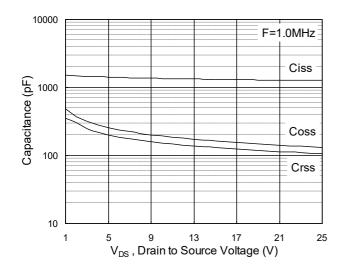


Fig.6 Normalized R_{DSON} vs. T_J



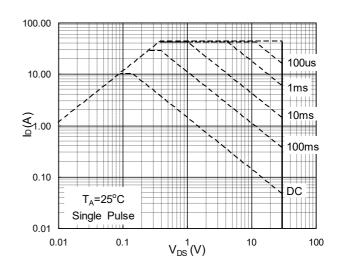


Fig.7 Capacitance

Fig.8 Safe Operating Area

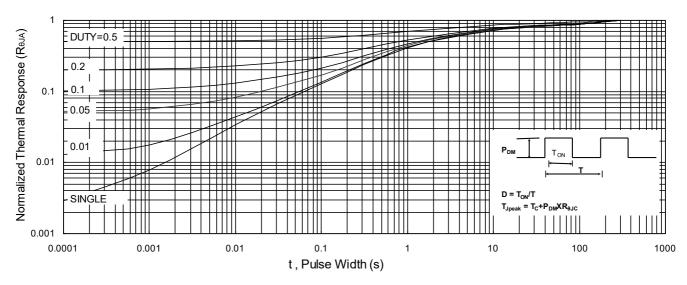


Fig.9 Normalized Maximum Transient Thermal Impedance

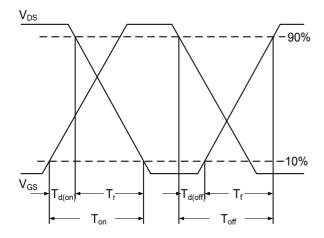


Fig.10 Switching Time Waveform

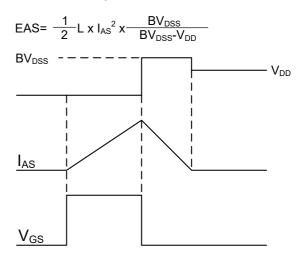
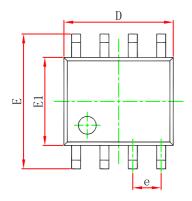
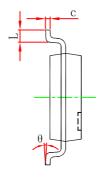


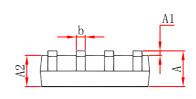
Fig.11 Unclamped Inductive Switching Waveform



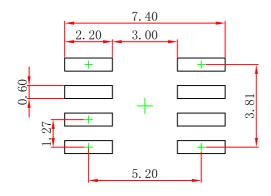
SOP-8 Package Outline Dimensions







| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | |
|--------|---------------------------|-------|----------------------|--------|--|
| Symbol | Min | Max | Min | Max | |
| A | 1. 350 | 1.750 | 0.053 | 0.069 | |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 | |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 | |
| b | 0.330 | 0.510 | 0.013 | 0. 020 | |
| c | 0.170 | 0.250 | 0.007 | 0.010 | |
| D | 4.800 | 5.000 | 0.189 | 0. 197 | |
| e | 1. 270 (| BSC) | 0.050 (BSC) | | |
| E | 5.800 | 6.200 | 0.228 | 0.244 | |
| E1 | 3.800 | 4.000 | 0.150 | 0.157 | |
| L | 0.400 | 1.270 | 0.016 | 0.050 | |
| θ | 0° | 8° | 0° | 8° | |



- Note: 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

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BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR
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